

U.S.S.N. 10,811,621

Claim Amendments

Please amend claims 1, 3, 7-9, 11, 15, 17-19 as follows:

Listing of Claims

1. (currently amended) An electrolyte bath comprising a suspension layer for forming a wetting layer on a substrate for copper electroplating, comprising:

an electrolyte solution; and

a composition comprising an organic acid and a non-ionic polymer mixed with said organic acid provided in said electrolyte solution;

wherein said composition forms a separated suspension layer within said electrolyte solution.

2. (original) The electrolyte of claim 1 wherein said organic acid is citric acid or acetic acid.

3. (currently amended) The electrolyte of claim 1 wherein said non-ionic polymer is an alcohol, an amine or alkylphenol alkoxylate.

4. (original) The electrolyte of claim 1 wherein said composition is present in said electrolyte solution in a concentration of

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about 5 % by weight.

5. (original) The electrolyte of claim 1 wherein said non-ionic polymer has a molecular weight of less than 1,000.

6. (original) The electrolyte of claim 5 wherein said organic acid is citric acid or acetic acid.

7. (currently amended) The electrolyte of claim 1 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

8. (currently amended) The electrolyte of claim 7 wherein said organic acid is citric acid or acetic acid and said non-ionic polymer is an alcohol, an amine or alkylphenol alkoxylate.

9. (currently amended) An electrolyte bath comprising a suspension layer for forming a wetting layer on substrate prior to [[for]] copper electroplating said substrate layer within said electrolyte, comprising:

an electrolyte solution; and

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a composition comprising an organic acid and a non-ionic polymer mixed with said organic acid ~~provided in;~~

wherein said composition forms a separated suspension layer within said electrolyte solution said suspension layer for forming a wetting layer on a substrate as said substrate is passed through said suspension layer.

10. (original) The electrolyte of claim 9 wherein said organic acid is citric acid or acetic acid.

11. (currently amended) The electrolyte of claim 9 wherein said non-ionic polymer is an alcohol, an amine or alkylphenol alkoxylate.

12. (original) The electrolyte of claim 11 wherein said composition is present in said electrolyte solution in a concentration of about 5% by weight.

13. (original) The electrolyte of claim 9 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in

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a wt.% of about 5.

14. (original) The electrolyte of claim 13 wherein said organic acid is citric acid or acetic acid.

15. (currently amended) The electrolyte of claim 13 wherein said non-ionic polymer is an alcohol, an amine or alkylphenol alkoxylate.

16. (original) The electrolyte of claim 15 wherein said organic acid is citric acid or acetic acid.

17. (currently amended) A method for electroplating a metal onto a surface in an electroplating electrolyte solution, comprising the steps of:

providing a composition mixture comprising an organic acid and a non-ionic polymer;

forming a suspension layer of said composition mixture within said electrolyte solution;

forming a wetting layer on said surface by passing said

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surface through said suspension layer and into said electrolyte solution; and

electroplating said metal onto said surface.

18. (currently amended) The method of claim 17 wherein said organic acid is citric acid or acetic acid and said non-ionic polymer is an alcohol, an amine or alkylphenol alkoxylate.

19. (currently amended) The method of claim 17 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

20. (original) The method of claim 17 further comprising a substrate and wherein said surface comprises a metal seed layer deposited on said substrate.